

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:

Kenichi FUNAMOTO et al

Serial Number: 09/395,179

Filed: September 14, 1999

For: PACKAGE FOR ELECTRONIC COMPONENT, LID MATERIAL FOR
PACKAGE LID, AND PRODUCTION METHOD FOR LID MATERIAL



FILE COPY

**ATTN: APPLICATION
BRANCH**

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9-8-00
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REQUEST FOR CORRECTED FILING RECEIPT

Assistant Commissioner for Patents
Washington, D.C. 20231

November 15, 1999

Sir:

Please supply the undersigned attorney with a corrected filing receipt of the above-identified application.

In reviewing the Official Filing Receipt, we noted a typographical error in the title. The title should read "PACKAGE FOR ELECTRONIC COMPONENT, LID MATERIAL FOR PACKAGE LID, AND PRODUCTION METHOD FOR LID MATERIAL", rather than "PACKAGE FOE ELECTRONIC COMPONENT, LID MATERIAL FOR PACKAGE LID, AND PRODUCTION METHOD FOR LID MATERIAL". We are enclosing a copy of the filing receipt and Declaration with the corrections highlighted in yellow.

In the event any fees are due with respect to this paper, please charge our Deposit Account No. 14-1060.

Respectfully submitted,

NIKAIDO, MARMELSTEIN, MURRAY & ORAM LLP

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Atty. Docket No. P7459-9002

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Enclosure: Copy of Filing Receipt and Declaration

FILING RECEIPT



UNITED STATES DEPARTMENT OF COMMERCE
Patent and Trademark Office
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APPLICATION NUMBER	FILING DATE	GRP ART UNIT	FIL FEE REC'D	ATTORNEY DOCKET NO.	DRWGS	TOT CL	IND CL
09/395,179	09/14/99	1725	\$832.00	P7459-9002	2	24	3

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Receipt is acknowledged of this nonprovisional Patent Application. It will be considered in its order and you will be notified as to the results of the examination. Be sure to provide the U.S. APPLICATION NUMBER, FILING DATE, NAME OF APPLICANT, and TITLE OF INVENTION when inquiring about this application. Fees transmitted by check or draft are subject to collection. Please verify the accuracy of the data presented on this receipt. If an error is noted on this Filing Receipt, please write to the Office of Initial Patent Examination's Customer Service Center. Please provide a copy of this Filing Receipt with the changes noted thereon. If you received a "Notice to File Missing Parts of Application" ("Missing Parts Notice") in this application, please submit any corrections to this Filing Receipt with your reply to the "Missing Parts Notice." When the PTO processes the reply to the "Missing Parts Notice," the PTO will generate another Filing Receipt incorporating the requested corrections (if appropriate).

Applicant(s) KENICHI FUNAMOTO, OSAKA, JAPAN; HIDETOSHI NODA, OSAKA, JAPAN; MASAOKI ISHIO, OSAKA, JAPAN.

FOREIGN APPLICATIONS-	JAPAN	10-268863	09/24/98
	JAPAN	11-218310	08/02/99

IF REQUIRED, FOREIGN FILING LICENSE GRANTED 10/04/99
TITLE

PACKAGE FOR ELECTRONIC COMPONENT, LID MATERIAL FOR PACKAGE LID, AND
PRODUCTION METHOD FOR LID MATERIAL

PRELIMINARY CLASS: 228

DATA ENTRY BY: HARRISON, BRUCE

TEAM: 06 DATE: 10/04/99

(See reverse for new important information)